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JUN 05 1998

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE GROUP 2100



Attorney Docket No. 040679/0439

In re patent application of  
Haruhiko MURATA et al. Group Art Unit: 2831  
Serial No. 08/825,400 Examiner: K. Soderquist  
Filed: March 28, 1997  
For: IMPROVEMENTS IN OR RELATING TO CIRCUIT BOARD FOR  
SOLDER BUMPS

6/10/98  
H/B  
JW

AMENDMENT AND REPLY UNDER 37 C.F.R. § 1.111

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In reply to the Office Action mailed March 04, 1998, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 5-11 and amend the following claims.

*B1*

1. (Amended) A circuit board comprising:  
a substrate having a joining surface; and  
a plurality of solder bumps disposed on said joining surface  
of said substrate in such a manner as to form a predetermined  
profiled line or surface pattern;  
wherein said solder bumps have tops which are free, flat and  
leveled [, and a coplanarity of said solder bumps is 0.5  $\mu$ m or  
less per 1 mm].

Claim 3 line 2, delete "nearly".